

Poster Session Exhibitor List (until 2 Oct 2006)

Category	Company	Country	Business Field
Design and Simulation	FLUENT ASIA PACIFIC CO.,LTD.	JAPAN	Simulation Tool
	NAGASE ELECTRONIC EQUIPMENT SERVICE CO.,LTD.	JAPAN	LSI Design Tool, Simulation Tool, DFMIT Design for Manufacturing and Integrative Technology
	Moldflow Japan K.K.	JAPAN	Moldflow Plastics Insight
	TOPPAN PRINTING CO.,LTD.	JAPAN	LSI Design, Trial Production Service of LSI
Wafer Process	TOSHIBA CORPORATION Semiconductor Company	JAPAN	IDM, Foundry, Packaging , Testing
	Renesas Technology Corp.	JAPAN	IDM , Next Generation SiP (Si via forming)
	Semiconductor Manufacturing International Corp. SMIC	CHINA	Foundry, Wafer Process
Assembling and Test Process	Renesas Kyushu Semiconductor Corp.	JAPAN	Packaging and Testing House, EMS
	STK TECHNOLOGY CO.,LTD.	JAPAN	Testing, Test House
	FUKURYO SEMICON ENGINEERING CORPORATION	JAPAN	Analysis for LSI, Advanced Analysis Technology Supporting SiP
	King Yuan Electronics Co., Ltd. KYEC	TAIWAN	Testing, Test House
	ALLVIA	U.S.A.	Packaging House, Cooper Plating Techniques For Through Wafer Vias
Equipment for Inspection	Kyushu Institute of Technology	JAPAN	Univ., Inspection Equipment for Semiconductor Devise
	Marubun Corporation	JAPAN	Agent, Inspection Equipment
	MORITANI & CO.,LTD	JAPAN	Agent, Equipment, Ion Migration Testing Systems
	SELASTAR Corp. / Technosem	JAPAN	Agent, Long Life Contact Probe (Twist Probe, Re-Test Free)
	Frontier Semiconductor Manufacturing	U.S.A.	Equipment, Metrology Tool for BEOL
Equipment for Manufacturing	Produce Co.,Ltd.	JAPAN	Equipment, Manufacture of Electronic Roll Printers
	INTERTEC CORP.	JAPAN	Agent, Equipment
	SAWA CORPORATION	JAPAN	Equipment, Metal Mask Washing Machine
	SHIBUYA KOGYO CO.,LTD.	JAPAN	Equipment for Ball Moulder and FC Bonder
Advanced Materials	SENJU METAL INDUSTRY Co.,LTD.	JAPAN	Material, Pn Free Solder for Semiconductor PKG
	PROCESS LAB. MICRON Co.,Ltd	JAPAN	Material, Metal Mask for Semiconductor Devise
	MALCOM Co.,Ltd.	JAPAN	Equipment, Reflow Machine for Cell Production System, Reflow Simulator
	ACHILLES CORPORATION	JAPAN	Agent, Material, Wafer Package System, Conductive materials, non-electrified plastics, color conductive mattresses, electrification-resistant painting
	Hitachi Chemical	JAPAN	New Material for PKG Substrate
	Hanyang University	KOREA	Univ., Spark Plasma Sintering of ZnS-SiO2 Sputtering
	Oak-Mitsui Technologies	U.S.A.	Material, Material for Embedded Capacitor
	Okmetic	FIINLAND	Material, Silicon Wafer Solution for MEMS
Substrate and Manufacturing Service	IBITECH CO.,LTD.	JAPAN	PCB, Interposer, Design and Trial Production Service for Interposer
	Wabo Electronics	JAPAN	PCB, Design and product of precision PCBs, OEM
	HITACHI ULSI Systems Co.,Ltd.	JAPAN	PCB, Design, JISSO Solutions
	KOA CORPORATION	JAPAN	Interposer, PCB, LTCC
	Oki Printed Circuits Co.,Ltd	JAPAN	PWB for Inspection and Testing for Semiconductor Device
	SANYO Co.,Ltd.	JAPAN	Agent, Precision FPC
	Hirai	JAPAN	LTCC Substrate (Low Temperature Cofired Ceramic, Malutilayer Substrate, Various Material Ething parts, Surface Treatment
	Imbera	FINLAND	PCB, Embedding Discrete Components inside PCB Structure